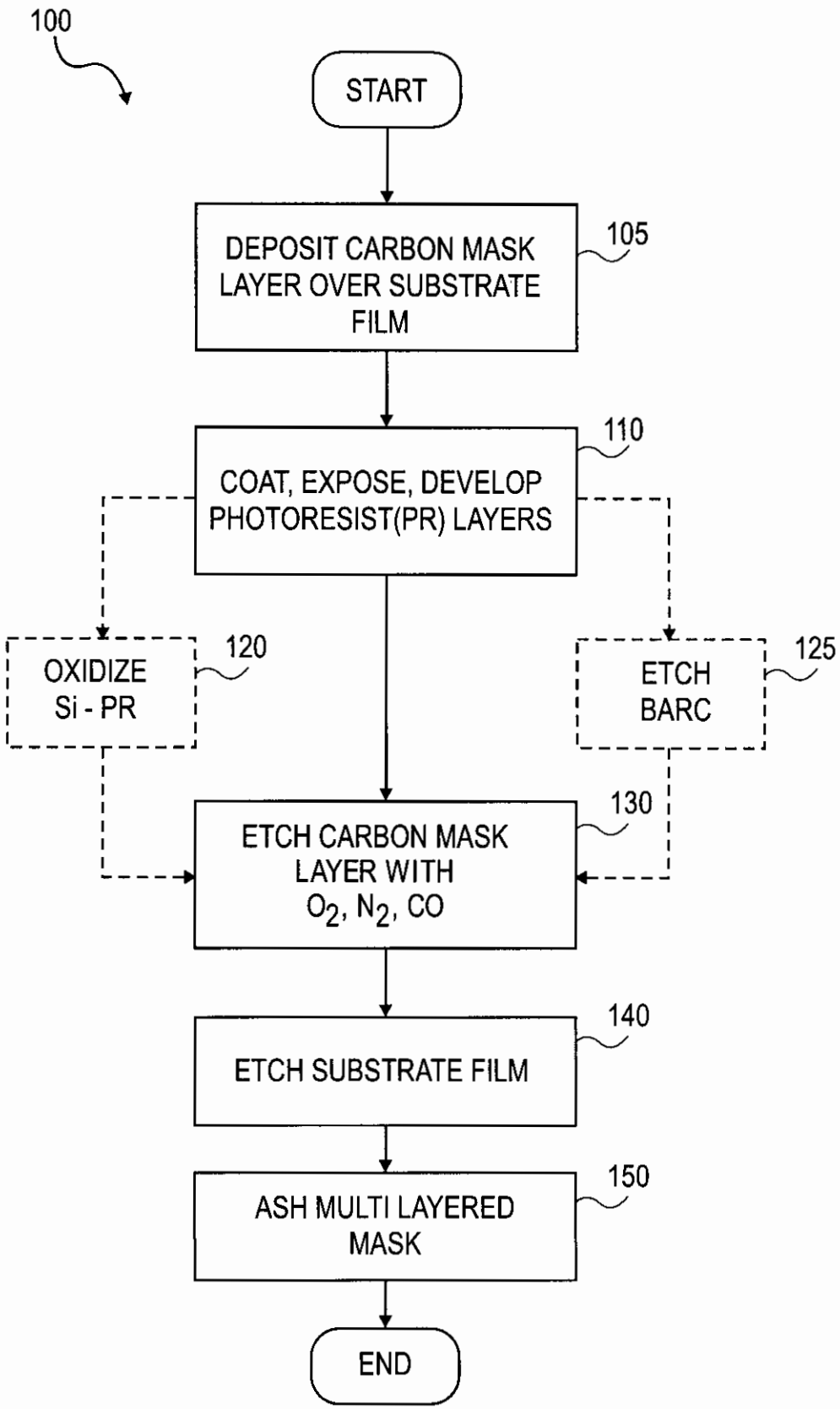

100
START
DEPOSIT CARBON MASK LAYER OVER SUBSTRATE FILM
105
COAT, EXPOSE, DEVELOP PHOTORESIST(PR) LAYERS
110
OXIDIZE Si - PR
120
ETCH BARC
125
ETCH CARBON MASK LAYER WITH O_2, N_2, CO
130
ETCH SUBSTRATE FILM
140
ASH MULTI LAYERED MASK
150
END

FIG. 1

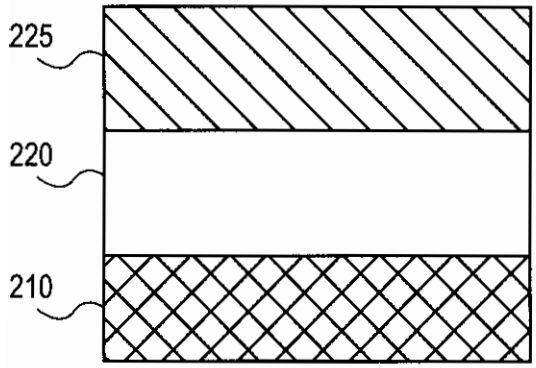


FIG. 2A

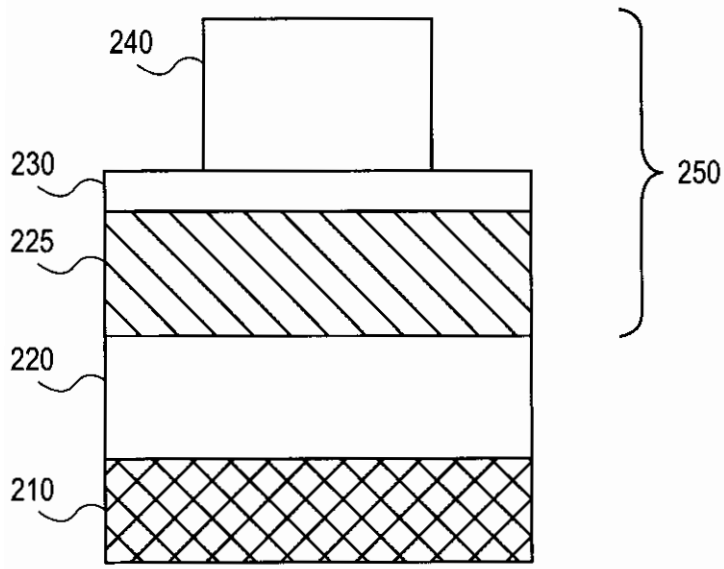


FIG. 2B

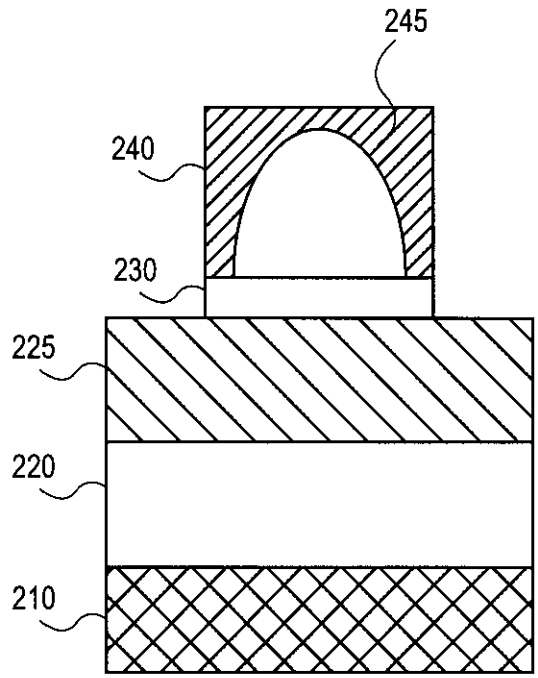


FIG. 2C

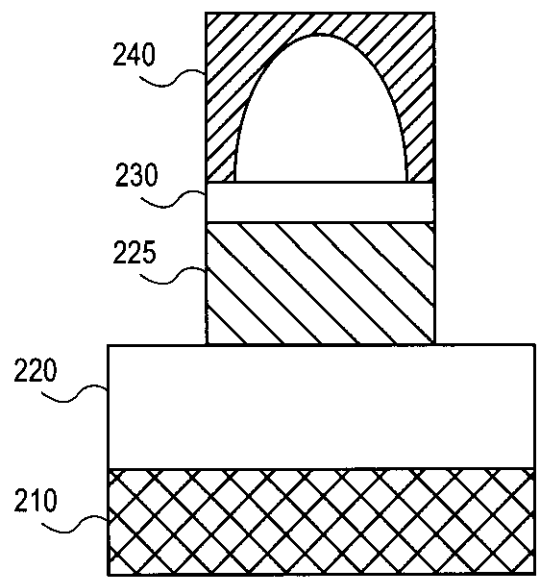


FIG. 2D

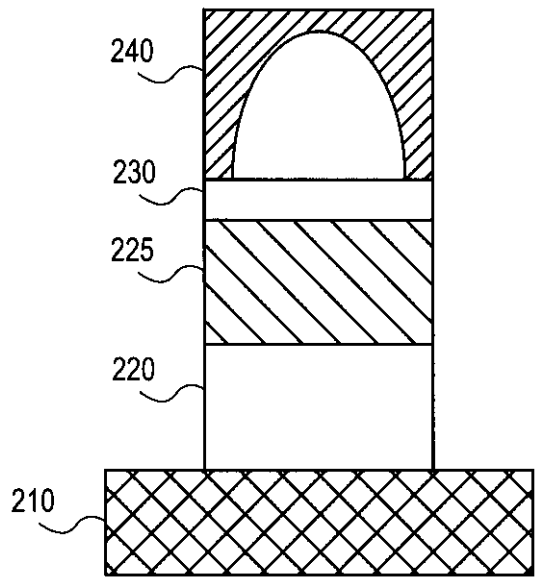


FIG. 2E

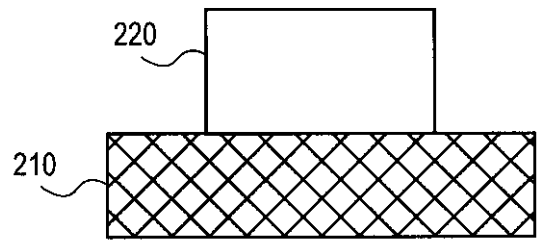


FIG. 2F

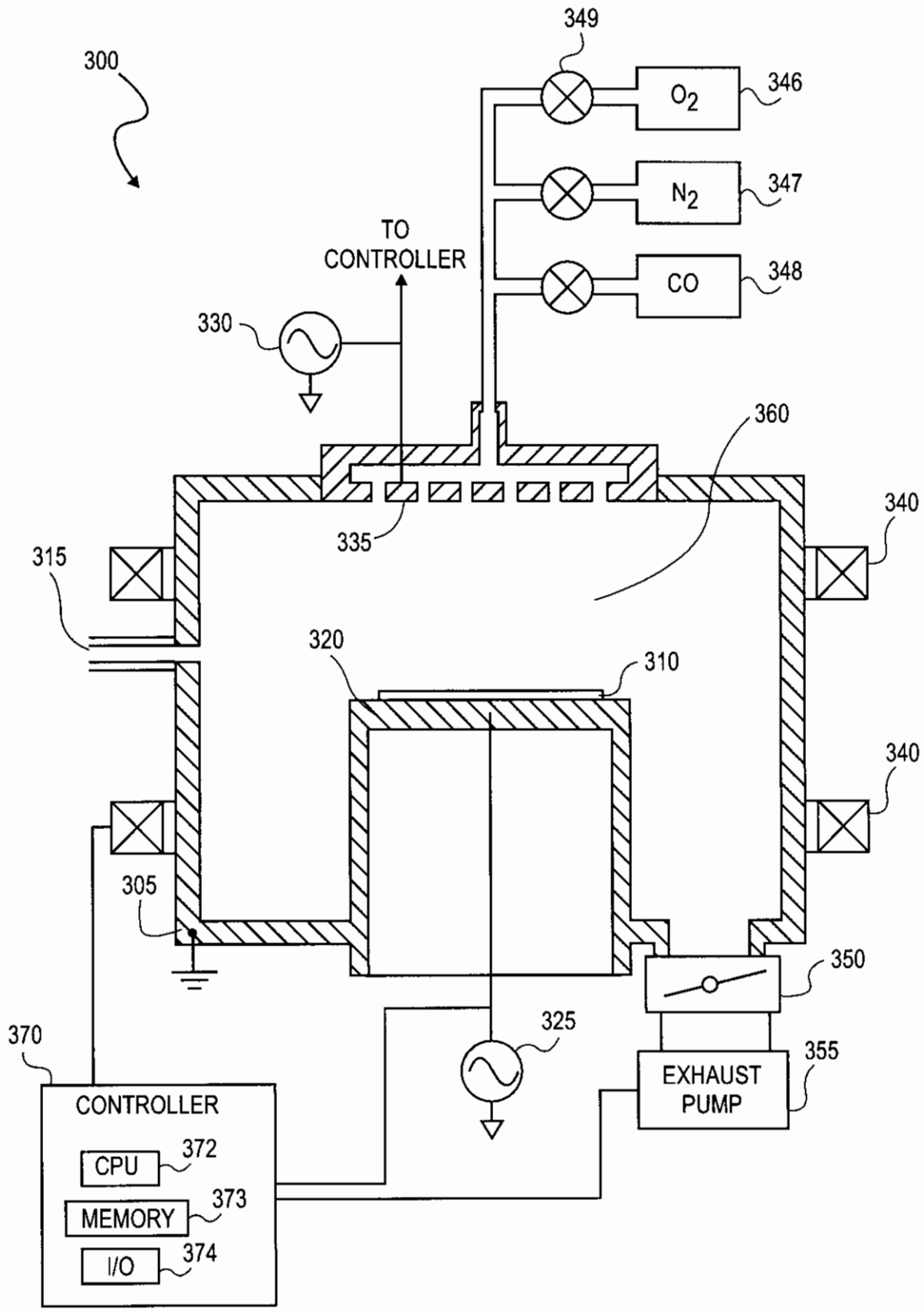

300
349
O_2
346
N_2
347
CO
348
TO CONTROLLER
330
360
335
340
315
320
310
340
305
350
325
370
355
EXHAUST PUMP
CONTROLLER
CPU
372
MEMORY
373
I/O
374

FIG. 3